

SMD Comm COG Flex, Ceramic, 330 pF, 5%, 250 VDC, COG, SMD, MLCC, FT-CAP, Ultra-Stable, 0603



Dimensions	
Chip Size	0603
L	1.6mm +/-0.17mm
W	0.8mm +/-0.15mm
T	0.8mm +/-0.15mm
S	0.58mm MIN
B	0.45mm +/-0.15mm

Packaging Specifications	
Packaging:	Bulk, Bag
Packaging Quantity:	1

General Information	
Series:	SMD Comm COG Flex
Style:	SMD Chip
Description:	SMD, MLCC, FT-CAP, Ultra-Stable
Features:	FT-CAP, Ultra-Stable
RoHS:	Yes
Termination:	Flexible Termination
Marking:	No
AEC-Q200:	No
Component Weight:	4600 ug
Shelf Life:	78 Weeks
MSL:	1

Specifications	
Capacitance:	330 pF
Measurement Condition:	1 MHz 1.0Vrms
Capacitance Tolerance:	5%
Voltage DC:	250 VDC
Dielectric Withstanding Voltage:	625 VDC
Temperature Range:	-55/+125°C
Temperature Coefficient:	COG
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC):	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor:	0.1% 1 MHz 1.0Vrms
Aging Rate:	0% Loss/Decade Hour
Insulation Resistance:	100 GOhms

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